

**Amendments To The Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

**IN THE CLAIMS:**

1. (Currently Amended) A cooling device for an electronic equipment, comprising:
  - a first cooling panel [(1)] wherein a first passage [(11)] through which refrigerant circulates is formed;
  - a second cooling panel [(2)] wherein a second passage [(21)] through which said refrigerant circulates is formed, said formed, said second cooling panel being disposed to oppose said first cooling panel [(1)]; and
  - a circulation pump [(3)] for circulating said refrigerant through said first passage [(1)] and said second passage [(2)] to thereby diffuse heat transferred to said first cooling panel [(1)] and said second cooling panel [(2)], wherein:
    - said first cooling panel [(1)] and said second cooling panel [(2)] sandwich therebetween an electronic circuit substrate.
2. (Currently Amended) The cooling device for an electronic equipment according to claim 1, further comprising a coupling member ~~(61, 62)~~ bearing said first cooling panel and said second cooling panel for opening and closing with respect to each other, and said connecting member has a flexibility.
3. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein at least one of said first cooling panel [(1)] and said second cooling panel

[[2)] includes a micro-channel structure [(12)] within said passage (11, 21), said micro-channel structure including a plurality of narrow passages having a width smaller than a width of said passage (11, 21).

4. (Currently Amended) The cooling device for an electronic equipment according to ~~any one of claims 1 to 3~~ claim 1, wherein said at least one of said first cooling panel [(1)] and said second cooling panel [(2)] includes an area [(13A)] in which an air-cooled fin [(13)] is formed on a surface thereof, said area [(13A)] being disposed downstream of said micro-channel structure [(12)].
5. (Currently Amended) The cooling device for an electronic equipment according to claim 4, wherein said passage in said area [(13A)] is wobbled.
6. (Currently Amended) The cooling device for an electronic equipment according to claim 4, wherein a cooling fan [(5)] is disposed corresponding to said air-cooled fin [(13)].
7. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein said circulation pump [(3)] is fixed onto a surface of said second cooling panel [(2)].
8. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein a reservoir [(4)] communicated with said second passage [(21)] is disposed on a surface of said second cooling panel [(2)].
9. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein a reservoir [(411)] communicated with said second passage [(21)] is formed within said second cooling panel [(2)].

10. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein at least one of said first cooling panel [(1)] and said second cooling panel [(2)] is formed by bonding together a top heat radiation panel [(23)] and a bottom heat radiation panel [(24)], in at least one of which is formed a groove [(23)].
11. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein said first cooling panel [(1)] has an area smaller than an area of said second cooling panel [(2)].
12. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein said first passage [(11)] has a width smaller than a width of said passage [(21)].
13. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein said first passage [(11)] has a depth larger than a depth of said second passage.
14. (Currently Amended) An electronic equipment mounting thereon the cooling device for electronic equipment according to ~~any one of claims 1 to 12~~ claim 1.